



SOT188-2

plastic leaded chip carrier; 68 leads

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	PLCC68
Package type industry code	PLCC68
Package style descriptive code	PLCC (plastic leaded chip carrier)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	112E10
JEDEC package outline code	MS-018
JEITA package outline code	EDR-7319
Mounting method type	S (surface mount)
Issue date	14-11-2001

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		24.13	-	24.18	24.33	mm
E	package width		24.13	-	24.18	24.33	mm
A	seated height		4.19	-	4.57	4.57	mm
A ₂	package height		[tbd]	-	3.81	[tbd]	mm
n ₂	actual quantity of termination		-	-	68	-	



2. Package outline

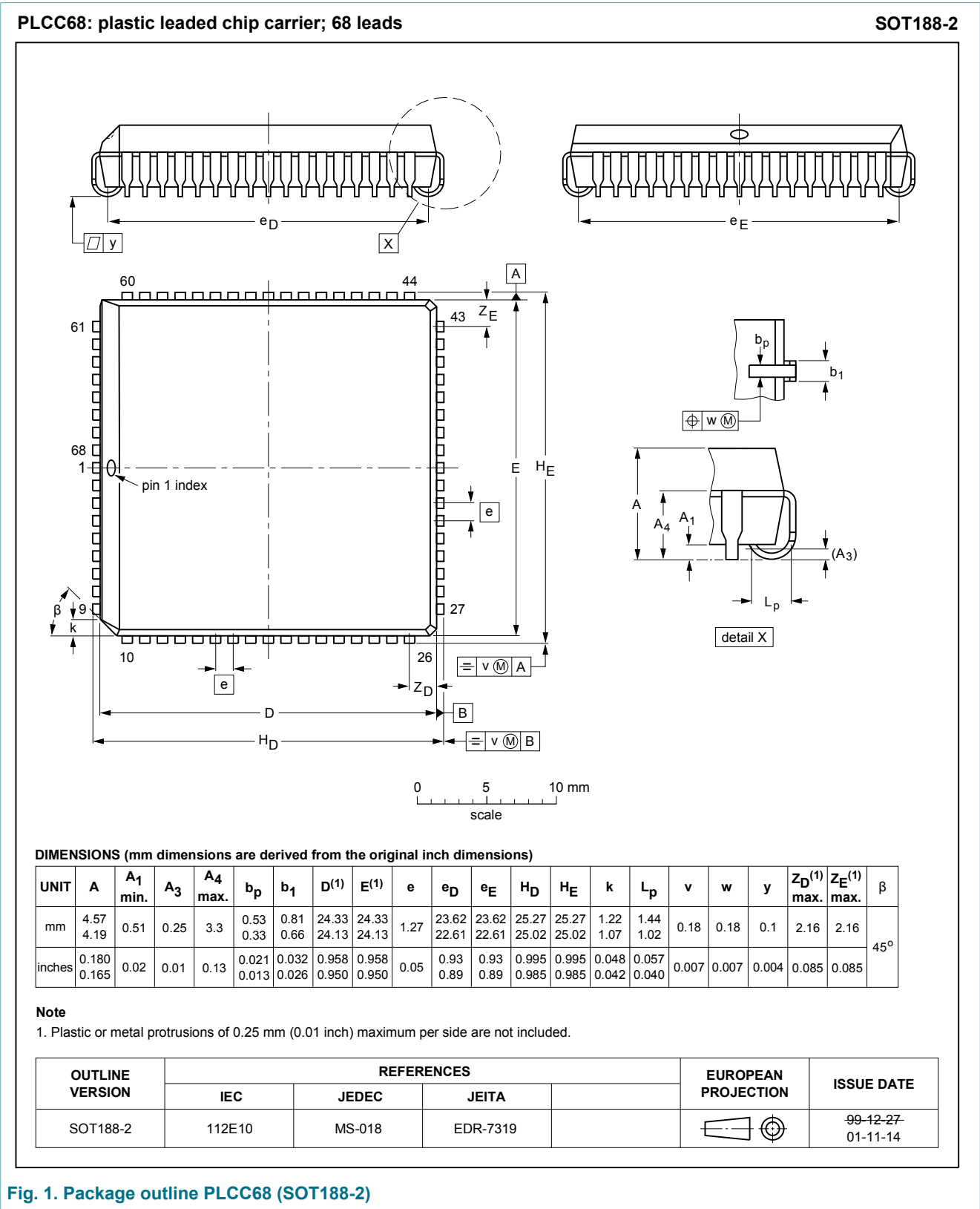


Fig. 1. Package outline PLCC68 (SOT188-2)

3. Soldering

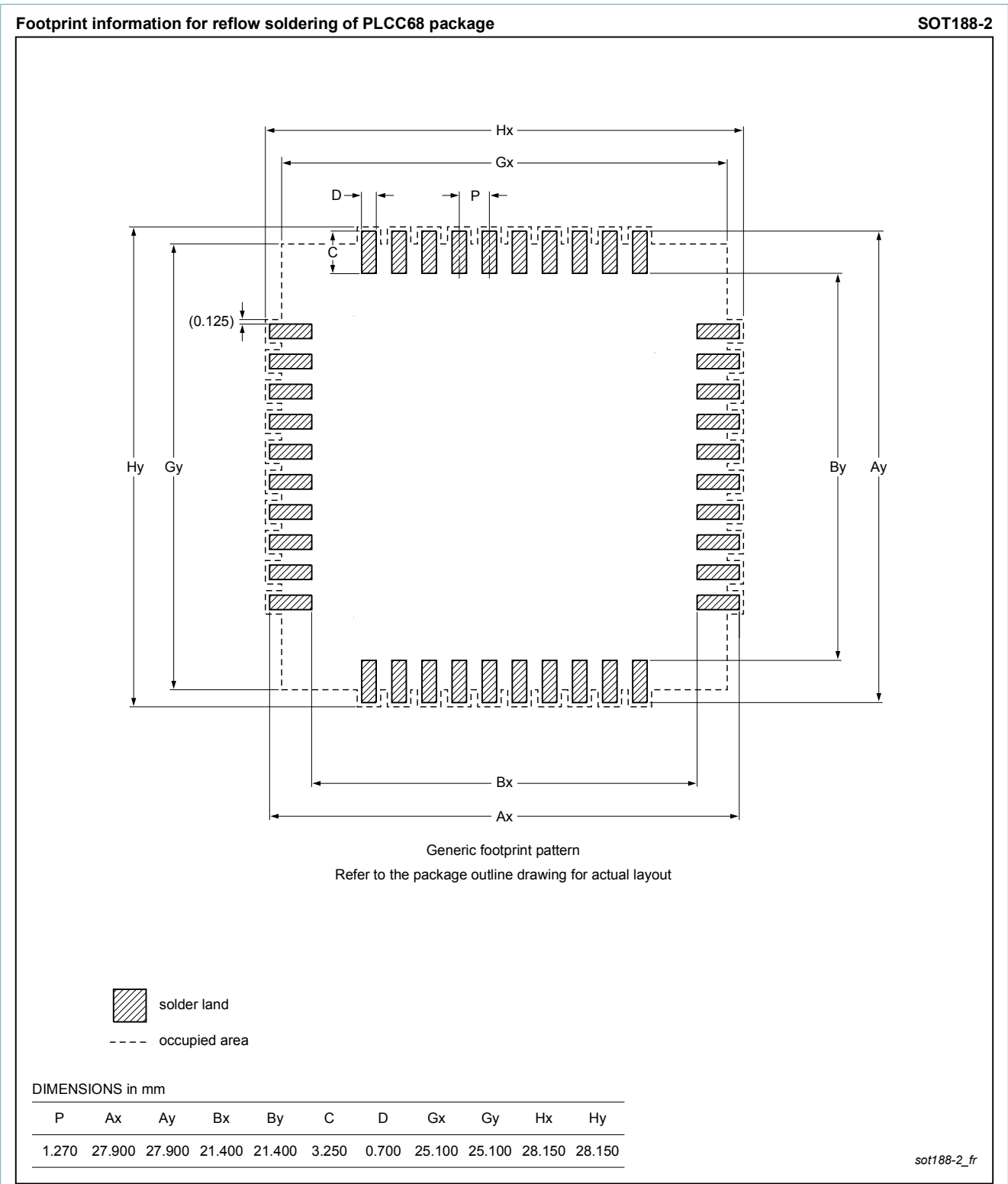


Fig. 2. Reflow soldering footprint for PLCC68 (SOT188-2)

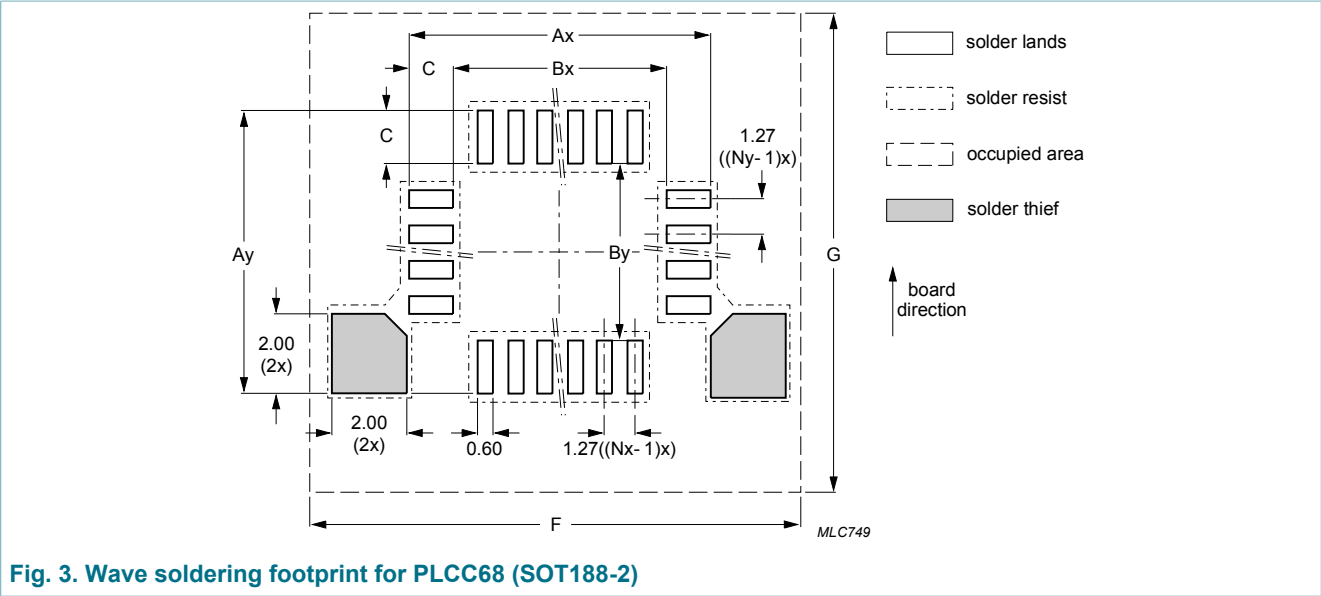


Fig. 3. Wave soldering footprint for PLCC68 (SOT188-2)

4. Legal information

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5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 5

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